

SiA519EDJ-T1-GE3-VB Datasheet

N- and P-Channel 30 V (D-S) MOSFET

PRODUCT SUMMARY

	V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)
N-Channel	30	0.018 at V _{GS} = 10 V	7 ^e	6.2
		0.020 at V _{GS} = 8 V	7 ^e	
		0.024 at V _{GS} = 4.5 V	7 ^e	
P-Channel	- 30	0.032 at V _{GS} = - 10 V	- 7 ^e	18.5
		0.034 at V _{GS} = - 8 V	- 7 ^e	
		0.040 at V _{GS} = - 4.5 V	- 6.5	

FEATURES

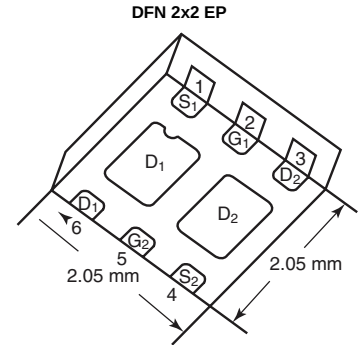
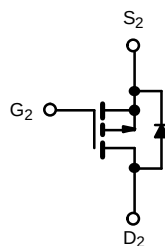
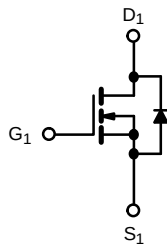
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Motor Drive
- Mobile Power Bank



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C, unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}	30	- 30	V
Gate-Source Voltage	V _{GS}	± 20	± 20	
Continuous Drain Current (T _J = 150 °C)	I _D	7 ^e	- 7 ^e	A
		6.2	- 6.2	
		6.2 ^{b, c}	- 6.0 ^{b, c}	
		5.2 ^{b, c}	- 5.0 ^{b, c}	
Pulsed Drain Current (10 μs Pulse Width)	I _{DM}	40	- 40	
Source-Drain Current Diode Current	I _S	2.6	- 2.6	
		1.6 ^{b, c}	- 1.6 ^{b, c}	
Pulsed Source-Drain Current	I _{SM}	40	- 40	
Single Pulse Avalanche Current	I _{AS}	10	- 20	
Single Pulse Avalanche Energy	E _{AS}	5	20	mJ
Maximum Power Dissipation	P _D	3.1	3.2	W
		2	2.1	
		2 ^{b, c}	2 ^{b, c}	
		1.28 ^{b, c}	1.28 ^{b, c}	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	N-Channel		P-Channel		Unit
		Typ.	Max.	Typ.	Max.	
Maximum Junction-to-Ambient ^{b, d}	R _{thJA}	50	62.5	47	62.5	°C/W
Maximum Junction-to-Foot (Drain)	R _{thJF}	30	40	29	38	

Notes:

a. Based on T_C = 25 °C.

b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under steady state conditions is 120 °C/W (n-channel) and 110 °C/W (p-channel).

e. Package limited.

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)									
Parameter	Symbol	Test Conditions		Min.	Typ. ^a	Max.	Unit		
Static									
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	N-Ch	30			V		
		V _{GS} = 0 V, I _D = - 250 μA	P-Ch	- 30					
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = 250 μA	N-Ch		40		mV/°C		
		I _D = - 250 μA	P-Ch		- 34				
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J	I _D = 250 μA	N-Ch		- 4.1			mV/°C	
		I _D = - 250 μA	P-Ch		5				
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	N-Ch	1.0		2.0	V		
		V _{DS} = V _{GS} , I _D = - 250 μA	P-Ch	- 1.0		- 2.0			
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 12 V	N-Ch			± 100	nA		
		V _{DS} = 0 V, V _{GS} = ± 12 V	P-Ch			± 100			
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V	N-Ch			1	μA		
		V _{DS} = - 30 V, V _{GS} = 0 V	P-Ch			- 1			
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C	N-Ch			10			
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C	P-Ch			- 10			
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	N-Ch	20			A		
		V _{DS} = - 5 V, V _{GS} = - 10 V	P-Ch	- 20					
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 6.8 A	N-Ch		0.018		Ω		
		V _{GS} = - 10 V, I _D = - 8 A	P-Ch		0.032				
		V _{GS} = 8 V, I _D = 6.7 A	N-Ch		0.020				
		V _{GS} = - 8 V, I _D = - 6.5 A	P-Ch		0.034				
		V _{GS} = 4.5 V, I _D = 6.6 A	N-Ch		0.024				
		V _{GS} = - 4.5 V, I _D = - 5 A	P-Ch		0.040				
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 6.8 A	N-Ch		27		S		
		V _{DS} = - 15 V, I _D = - 6.7 A	P-Ch		25				
Dynamic ^a									
Input Capacitance	C _{iss}	N-Channel V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz P-Channel V _{DS} = - 20 V, V _{GS} = 0 V, f = 1 MHz	N-Ch		510		pF		
Output Capacitance	C _{oss}		P-Ch		620				
			N-Ch		95				
Reverse Transfer Capacitance	C _{rss}		P-Ch		115				
		N-Ch		33					
Total Gate Charge	Q _g	N-Channel V _{DS} = 20 V, V _{GS} = 10 V, I _D = 10 A P-Channel V _{DS} = - 20 V, V _{GS} = - 10 V, I _D = - 10 A N-Channel V _{DS} = 20 V, V _{GS} = 4.5 V, I _D = 10 A P-Channel V _{DS} = - 20 V, V _{GS} = - 4.5 V, I _D = - 10 A	N-Ch		6	10	nC		
			P-Ch		41.5	63			
			N-Ch		5.8	7			
			P-Ch		16	22			
			Gate-Source Charge	Q _{gs}	N-Ch			1.6	
			Gate-Drain Charge	Q _{gd}	P-Ch			4.3	
N-Ch		1.4							
Gate Resistance	R _g	f = 1 MHz	N-Ch	0.3	1.1	2.3	Ω		
			P-Ch	1.2	5.7	9.6			

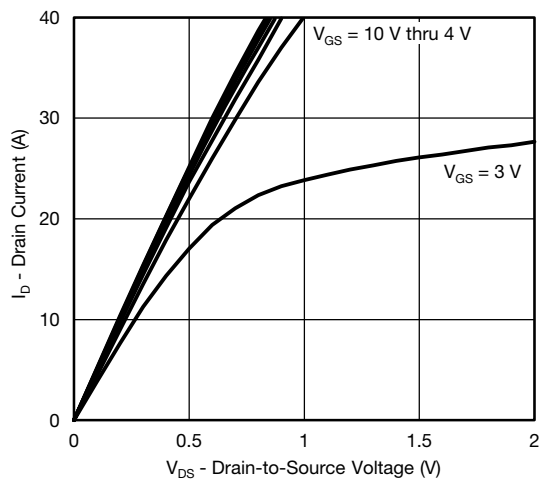
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions		Min.	Typ. ^a	Max.	Unit
Dynamic ^a							
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 20 V, R _L = 3.7 Ω I _D ≅ 5.4 A, V _{GEN} = 10 V, R _g = 1 Ω	N-Ch		4	8	ns
			P-Ch		10	16	
Rise Time	t _r		N-Ch		10	17	
			P-Ch		9	15	
Turn-Off Delay Time	t _{d(off)}	P-Channel V _{DD} = - 20 V, R _L = 2 Ω I _D ≅ - 10 A, V _{GEN} = - 10 V, R _g = 1 Ω	N-Ch		16	22	
			P-Ch		23	26	
Fall Time	t _f		N-Ch		5	9	
			P-Ch		10	16	
Turn-On Delay Time	t _{d(on)}	N-Channel V _{DD} = 20 V, R _L = 3.7 Ω I _D ≅ 5.4 A, V _{GEN} = 4.5 V, R _g = 1 Ω	N-Ch		10	16	
			P-Ch		26	35	
Rise Time	t _r		N-Ch		11	20	
			P-Ch		16	26	
Turn-Off Delay Time	t _{d(off)}	P-Channel V _{DD} = - 20 V, R _L = 2 Ω I _D ≅ - 10 A, V _{GEN} = - 4.5 V, R _g = 1 Ω	N-Ch		13	22	
			P-Ch		16	26	
Fall Time	t _f		N-Ch		5	9	
			P-Ch		16	26	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	N-Ch			2.6	A
			P-Ch			- 2.6	
Pulse Diode Forward Current ^a	I _{SM}		N-Ch			40	
			P-Ch			- 40	
Body Diode Voltage	V _{SD}	I _S = 5.4 A	N-Ch		0.81	1.2	V
		I _S = - 2 A	P-Ch		- 0.77	- 1.2	
Body Diode Reverse Recovery Time	t _{rr}	N-Channel I _F = 5 A, dI/dt = 100 A/μs, T _J = 25 °C	N-Ch		12	25	ns
			P-Ch		31	57	
Body Diode Reverse Recovery Charge	Q _{rr}		N-Ch		10	17	nC
			P-Ch		29	47	
Reverse Recovery Fall Time	t _a	P-Channel I _F = - 5 A, dI/dt = - 100 A/μs, T _J = 25 °C	N-Ch		10		ns
			P-Ch		13		
Reverse Recovery Rise Time	t _b		N-Ch		7		
			P-Ch		23		

Notes:

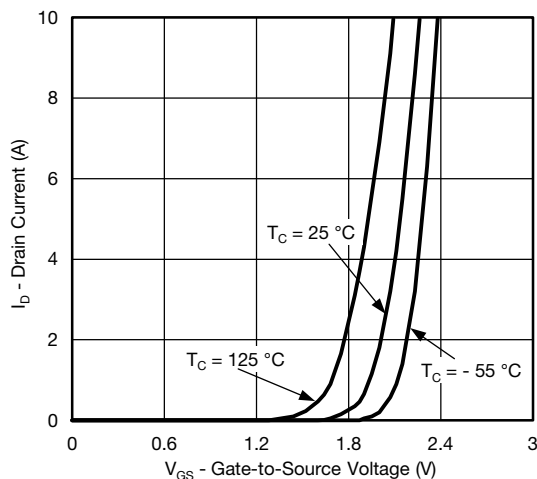
a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

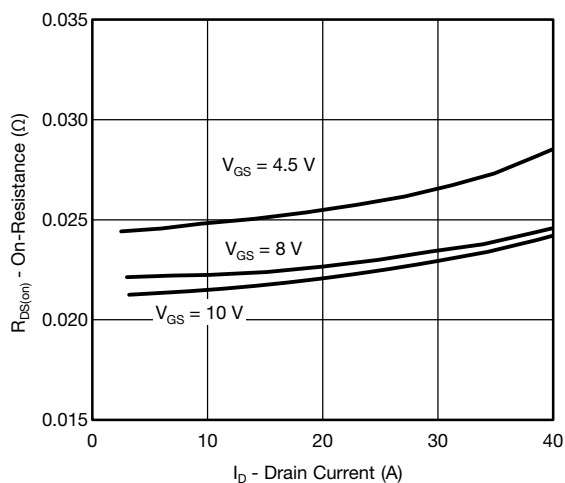
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


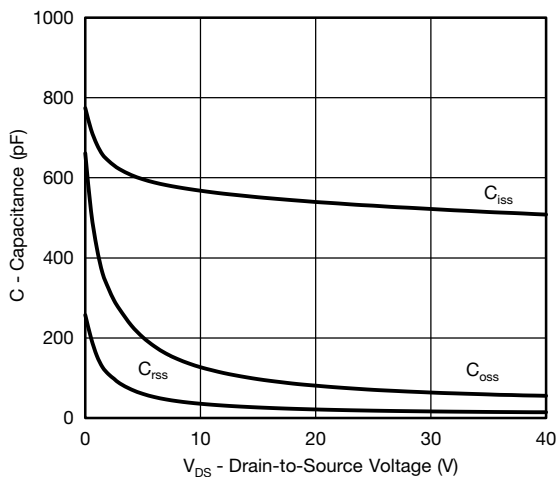
Output Characteristics



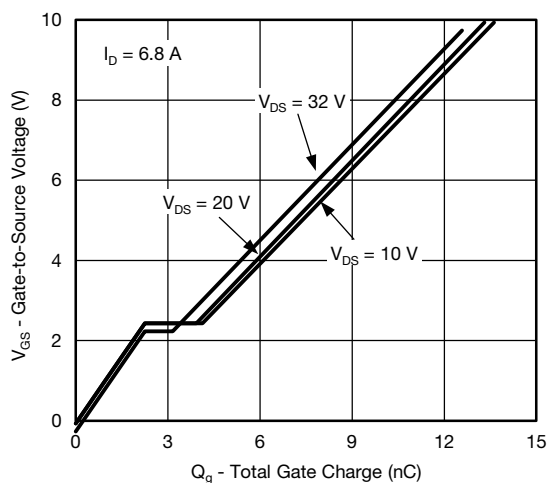
Transfer Characteristics



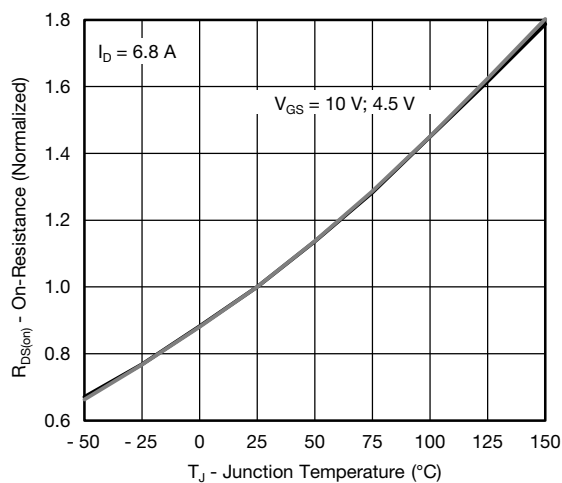
On-Resistance vs. Drain Current and Gate Voltage



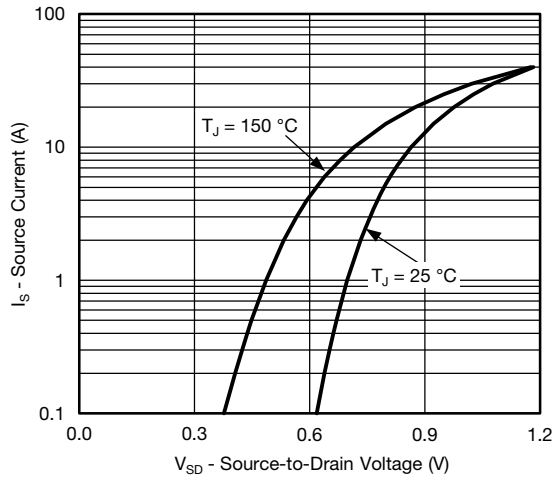
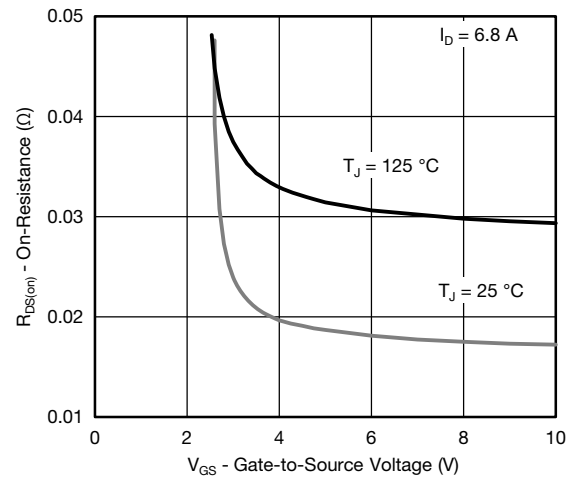
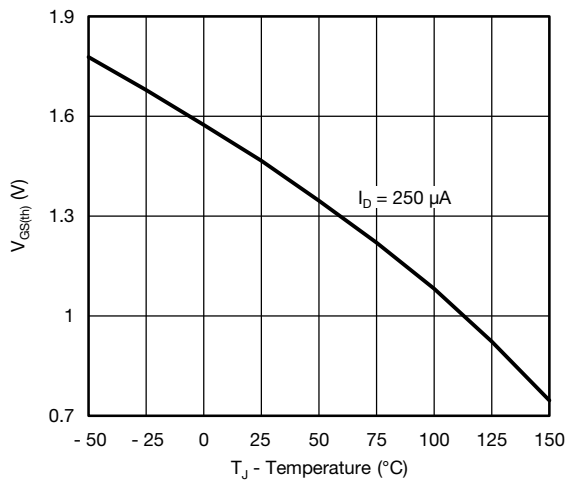
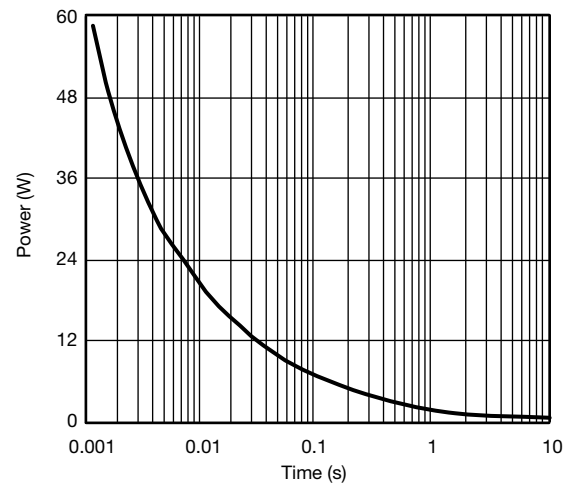
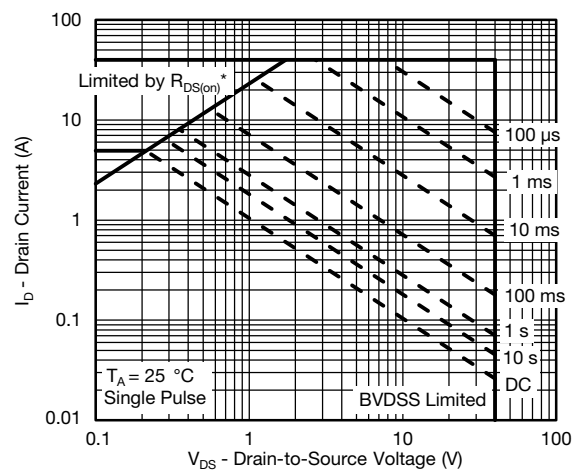
Capacitance



Gate Charge

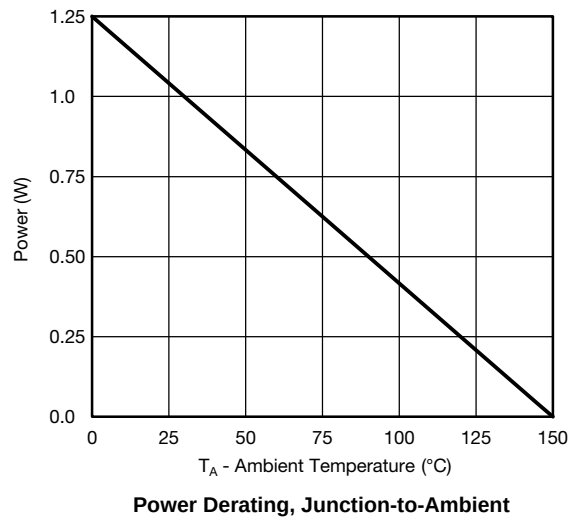
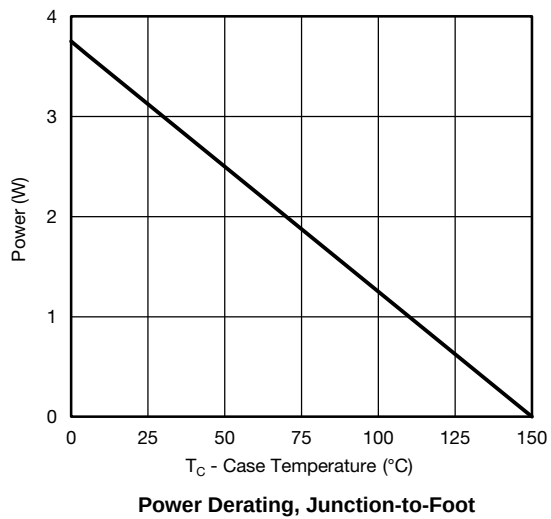
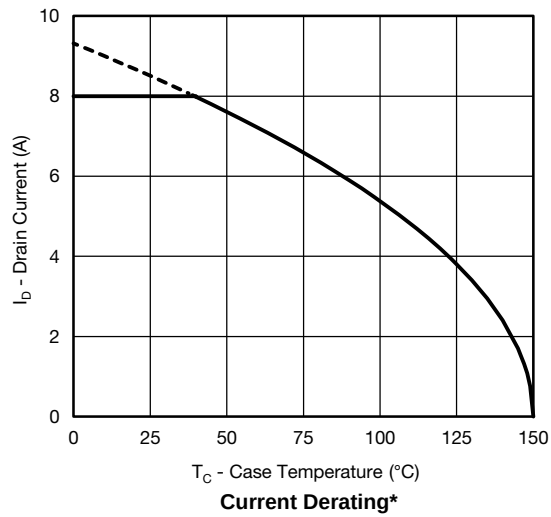


On-Resistance vs. Junction Temperature

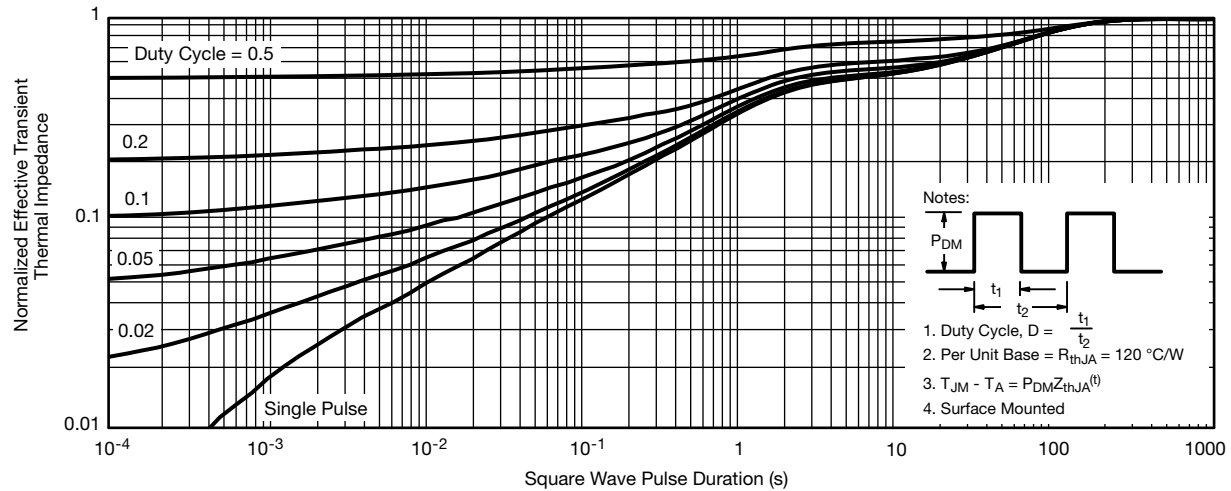
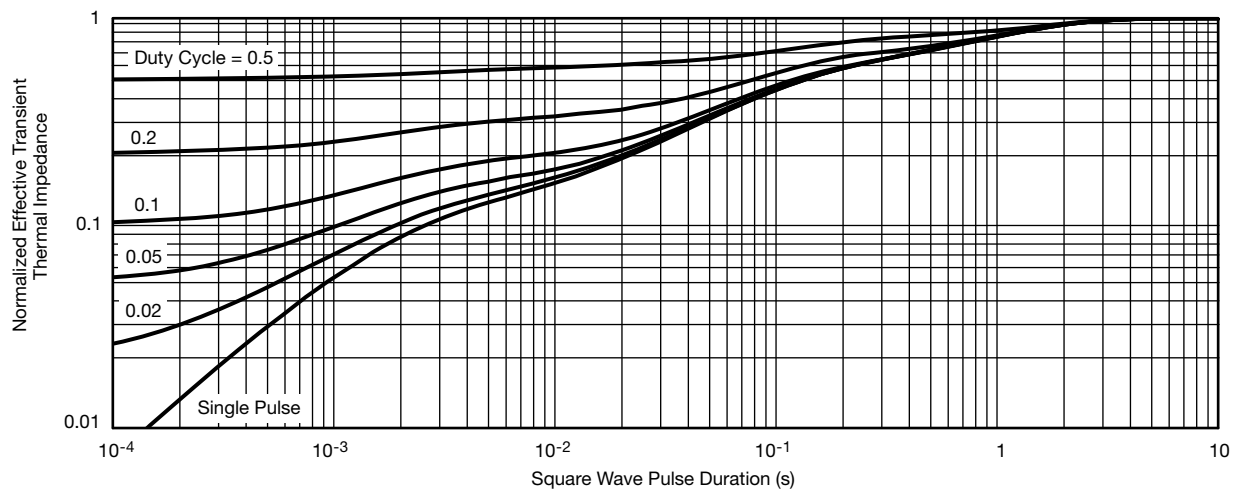
N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

Threshold Voltage

Single Pulse Power, Junction-to-Ambient


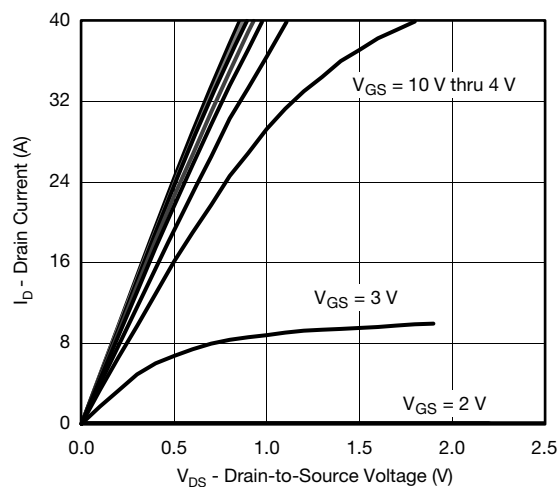
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

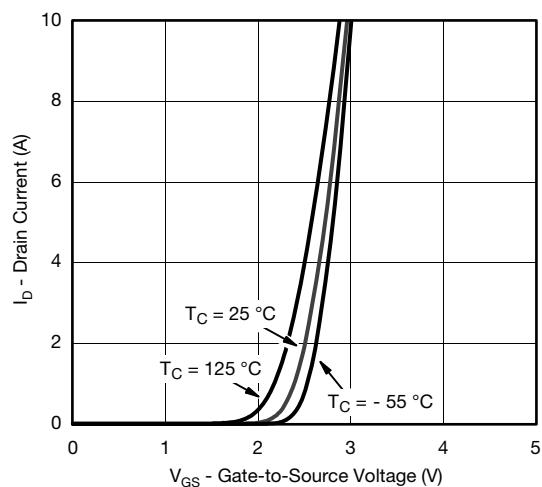
N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

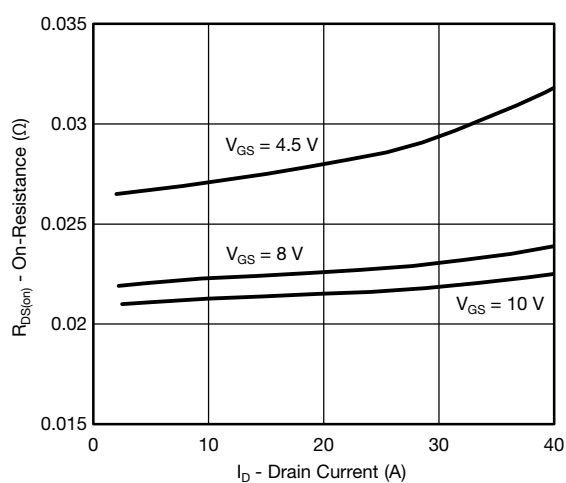
N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Thermal Transient Impedance, Junction-to-Foot

P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


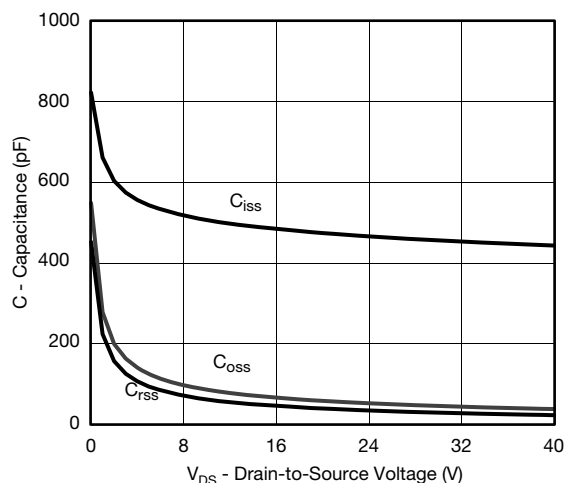
Output Characteristics



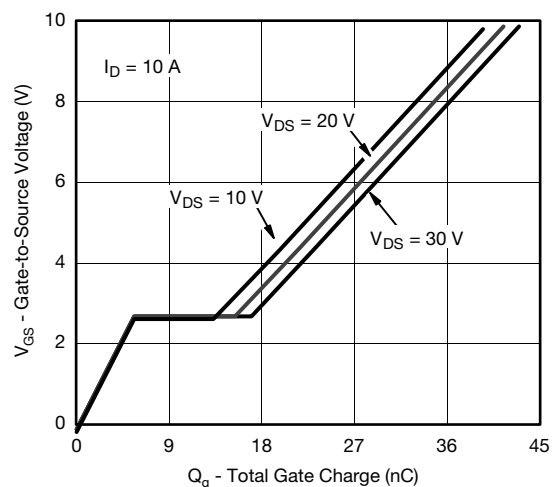
Transfer Characteristics



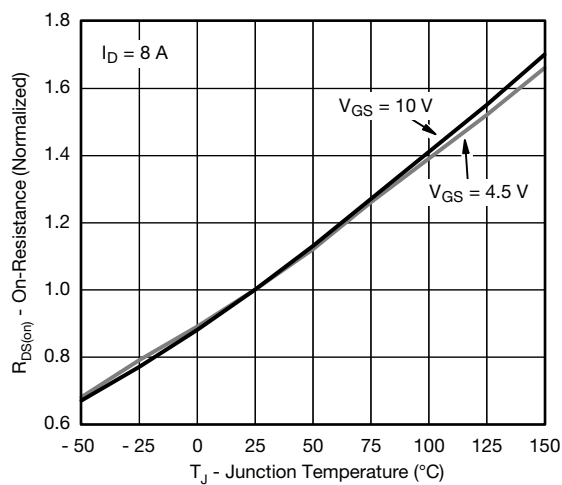
On-Resistance vs. Drain Current and Gate Voltage



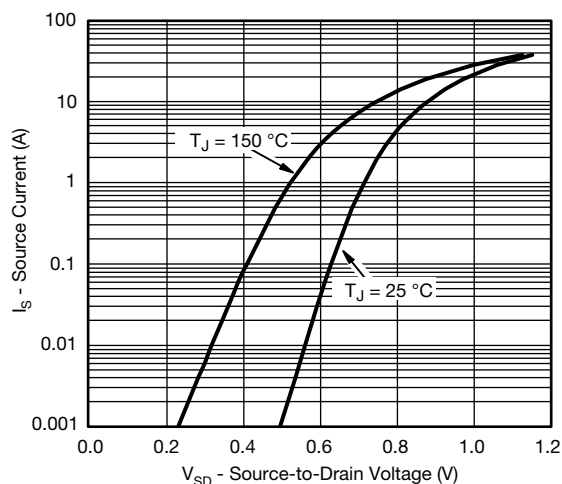
Capacitance



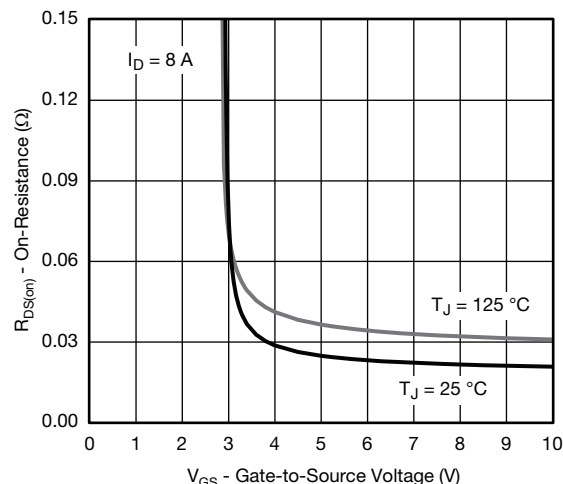
Gate Charge



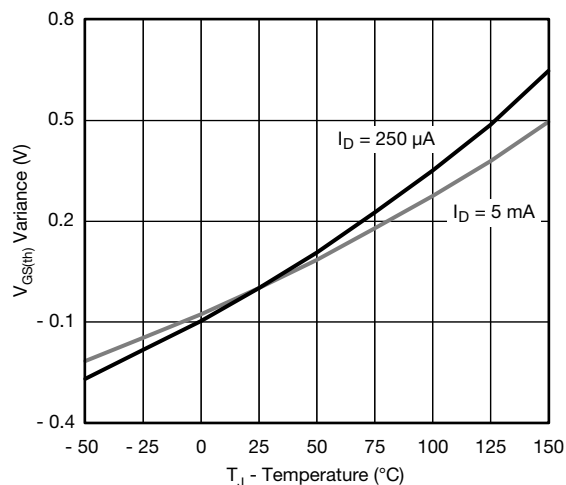
On-Resistance vs. Junction Temperature

P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)


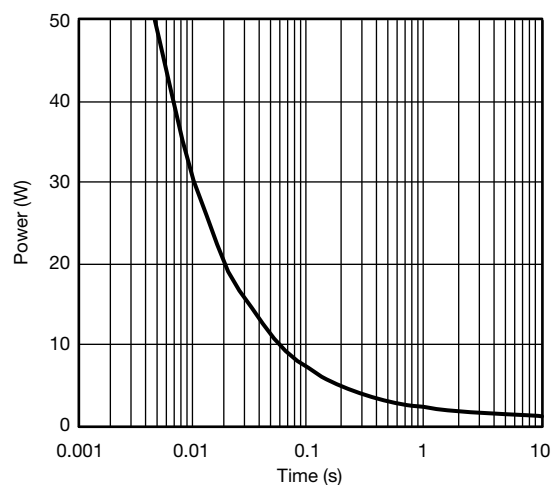
Source-Drain Diode Forward Voltage



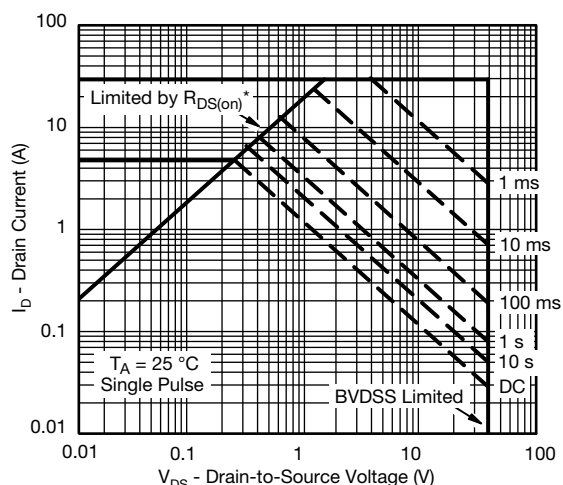
On-Resistance vs. Gate-to-Source Voltage



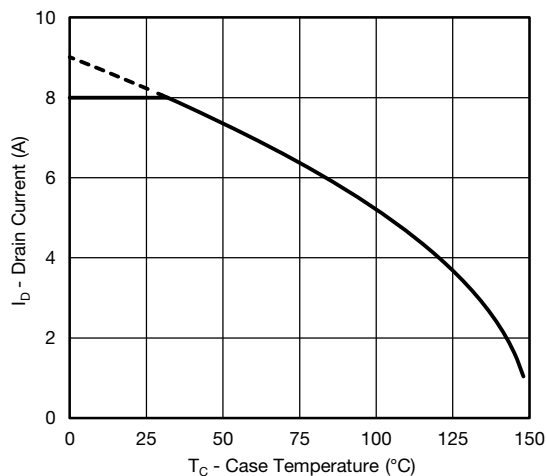
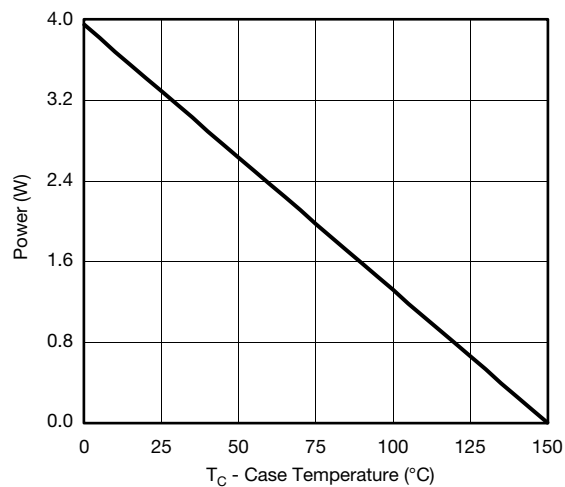
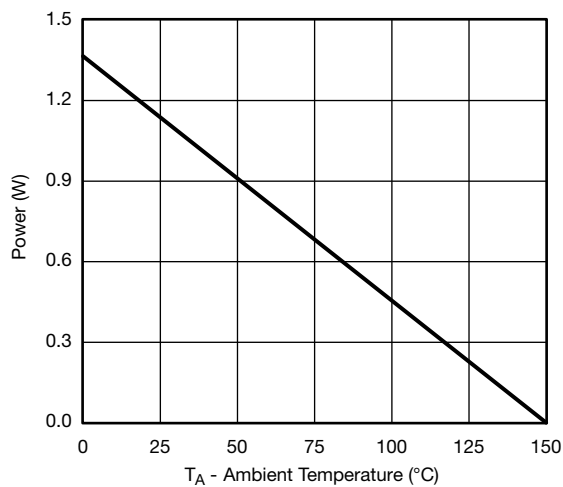
Threshold Voltage



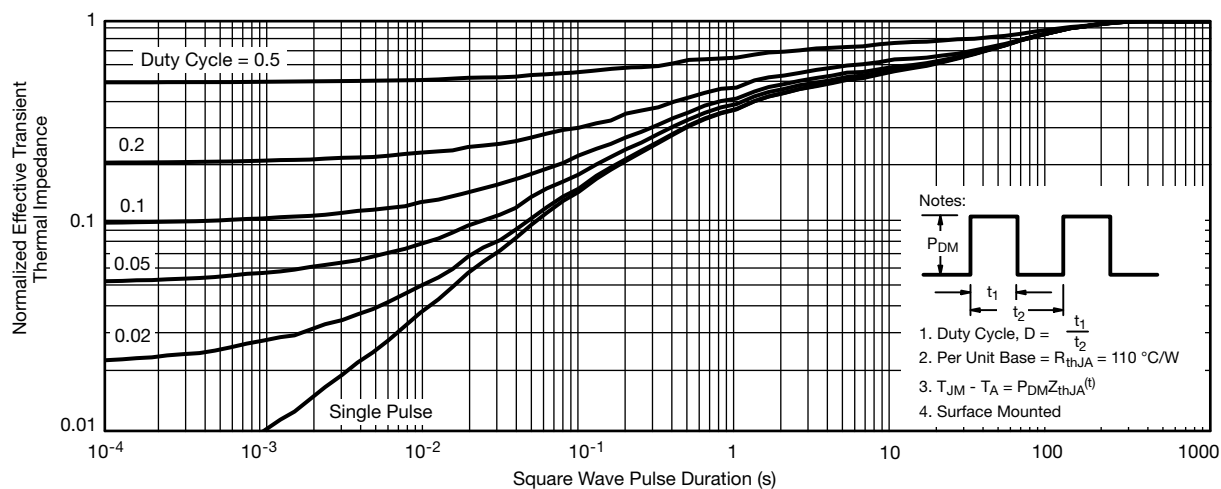
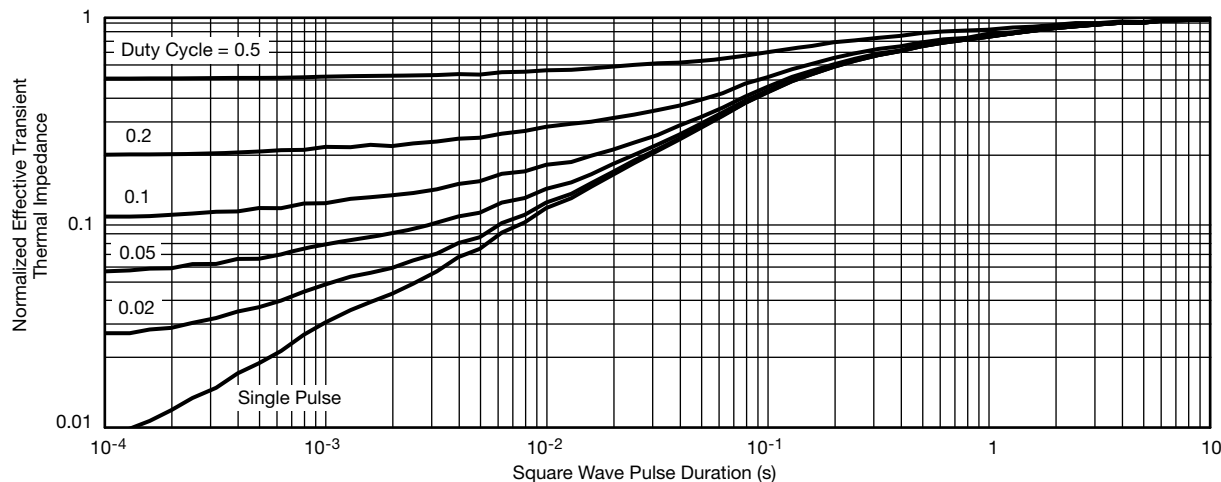
Single Pulse Power, Junction-to-Ambient

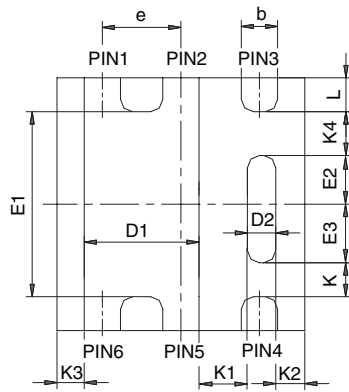


* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified
Safe Operating Area, Junction-to-Ambient

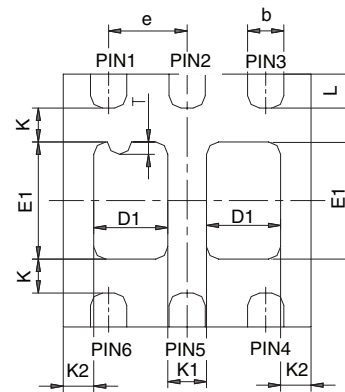
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Current Derating*

Power Derating, Junction-to-Foot

Power Derating, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

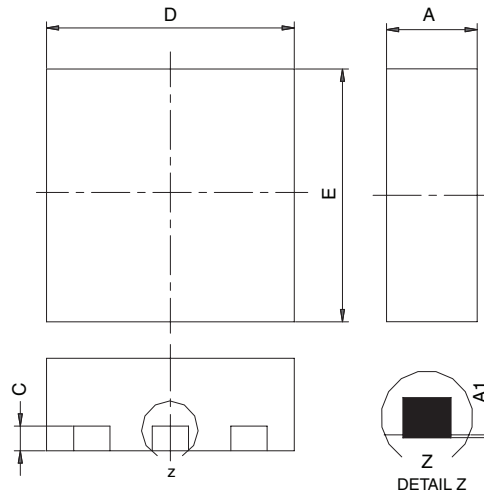
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Thermal Transient Impedance, Junction-to-Foot

DFN 2x2

BACKSIDE VIEW OF SINGLE



BACKSIDE VIEW OF DUAL



Notes:

1. All dimensions are in millimeters
2. Package outline exclusive of mold flash and metal burr
3. Package outline inclusive of plating

DIM	SINGLE PAD						DUAL PAD					
	MILLIMETERS			INCHES			MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
C	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
e	0.65 BSC			0.026 BSC			0.65 BSC			0.026 BSC		
K	0.275 TYP			0.011 TYP			0.275 TYP			0.011 TYP		
K1	0.400 TYP			0.016 TYP			0.320 TYP			0.013 TYP		
K2	0.240 TYP			0.009 TYP			0.252 TYP			0.010 TYP		
K3	0.225 TYP			0.009 TYP								
K4	0.355 TYP			0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
T							0.05	0.10	0.15	0.002	0.004	0.006
ECN: C-07431 – Rev. C, 06-Aug-07												
DWG: 5934												

Figure 1 is a technical drawing of a 3D-printed part, showing a top-down view. The drawing includes dimensions in millimeters (mm) and inches (in) for various features and overall size.

Overall Dimensions:

- Overall Width: 2.500 (0.098) mm
- Overall Height: 2.500 (0.098) mm

Central Hole Dimensions:

- Hole Width: 0.613 (0.024) mm
- Hole Height: 0.950 (0.037) mm

Feature Dimensions and Positions:

- Top-left feature: Width 0.300 (0.012) mm, Height 0.325 (0.013) mm.
- Top-middle feature: Width 0.350 (0.014) mm, Height 0.325 (0.013) mm.
- Top-right feature: Width 0.350 (0.014) mm, Height 0.325 (0.013) mm.
- Bottom-left feature: Width 0.350 (0.014) mm, Height 0.325 (0.013) mm.
- Bottom-middle feature: Width 0.350 (0.014) mm, Height 0.325 (0.013) mm.
- Bottom-right feature: Width 0.350 (0.014) mm, Height 0.325 (0.013) mm.
- Central hole: Width 0.613 (0.024) mm, Height 0.950 (0.037) mm.
- Feature below central hole: Width 0.160 (0.006) mm, Height 0.275 (0.011) mm.
- Feature to the right of central hole: Width 0.650 (0.026) mm, Height 0.275 (0.011) mm.

The drawing also includes a scale bar indicating 1 mm.

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